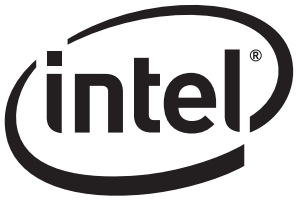

Intel® Desktop Board DG33TL

Specification Update

May 2008

Order Number E11661-003US

The Intel® Desktop Board DG33TL may contain design defects or errors known as errata, which may cause the product to deviate from published specifications. Current characterized errata are documented in this Specification Update.

Revision History

Revision	Revision History	Date
-001	This document is the first Specification Update for the Intel® Desktop Board DG33TL.	June 4, 2007
-002	Added Specification Changes 1 & 2 and updated General Information Table.	September 2007
-003	Updated General Information and Specification Changes Sections.	May 2008

Contents

Specification Update for the Intel® Desktop Board DG33TL

This document is an update to the specifications contained in the *Intel® Desktop Board DG33TL Technical Product Specification* (Order Number: D95738). It is intended for hardware system manufacturers and software developers of applications, operating systems, or tools. It will contain Specification Changes, Errata, Specification Clarifications, and Documentation Changes.

For specification updates concerning the Intel processor that may apply to this desktop board, refer to the following:

- *Intel® Core™2 Extreme Quad-Core Processor QX6000Δ Sequence and Intel® Core™2 Quad Processor Q6000Δ Sequence Specification Update* (Order Number: 315593)
- *Intel® Core™2 Extreme Processor X6800Δ and Intel® Core™2 Duo Desktop Processor E6000Δ and E4000Δ Sequence Specification Update* (Order Number: 313279)
- *Intel® Pentium® Dual-Core Desktop Processor E2000Δ Sequence Specification Update* (Order Number: 316982)
- *Intel® Celeron® Processor 400Δ Sequence Specification Update* (Order Number: 316964)

Unless otherwise noted in this document, it should be assumed that any processor errata for a given stepping are applicable to the Altered Assembly (AA) revision(s) associated with that stepping.

Refer to the *Intel® G33 Chipset Specification Update* (Order Number: 316967) for specification updates concerning the 82G33 GMCH Controller and that may apply to the desktop board DG33TL. Unless otherwise noted in this document, it should be assumed that any MCH errata for a given stepping are applicable to the Altered Assembly (AA) revision(s) associated with that stepping.

Refer to the *Intel® IO Controller Hub9 (ICH9) Family Specification Update* (Order Number: 316973) for specification updates concerning the 82801IR I/O Controller Hub and that may apply to the desktop board DG33TL. Unless otherwise noted in this document, it should be assumed that any ICH9 errata for a given stepping are applicable to the Altered Assembly (AA) revision(s) associated with that stepping.

Terminology

Specification Changes are modifications to the current published specifications. These changes will be incorporated in the next release of the specifications.

Errata are design defects or errors. Characterized errata may cause the desktop board behavior to deviate from published specifications. Hardware and software designed to be used with any given Altered Assembly (AA) and BIOS revision level must assume that all errata documented for that AA and BIOS revision level are present on all desktop boards.

Specification Clarifications describe a specification in greater detail or further highlight a specification's impact to a complex design situation. These clarifications will be incorporated in the next release of the specifications.

Documentation Changes include typos, errors, or omissions from the current published specifications. These changes will be incorporated in the next release of the specifications.

General Information

Basic Desktop Board DG33TL Identification Information

AA Revision	BIOS Revision	Notes
D89517-600	DPP3510J.86A.0216	1,2
D89517-700	DPP3510J.86A.0216	1,2
D89517-801	DPP3510J.86A.0216	1,2
D89517-802	DPP3510J.86A.0216	1,2
D89517-803	DPP3510J.86A.0293	1,2
D89517-804	DPP3510J.86A.0413	1,2

Notes:

1. The AA number is found on a small label on the component side of the board.
2. The G33 Chipset kit used on this AA revision consists of two components as follows:

Device	Stepping	S-Spec Numbers
82G33	A2	SLA9Q
82801IR	A2	SLA9N

Summary of Changes

The following table indicates the Specification Changes, Errata, Specification Clarifications, or Documentation Changes that apply to the Intel® Desktop Board DG33TL. Intel intends to fix some of the errata in a future revision of the desktop board, and to account for the other outstanding issues through documentation or specification changes as noted.

The following notations are used in the table:

Doc:	Document change or update that will be implemented.
PlanFix:	This erratum may be fixed in a future revision of the desktop board, driver, or BIOS.
Fixed:	This erratum has been previously fixed.
NoFix:	There are no plans to fix this erratum.
Shaded:	This erratum is either new or modified from the previous version of the document.

No.	Plans	Specification Changes
1	Doc	Table 1 of the technical specification will be updated to add the word “Micro” before ATX in Form Factor.
2	Doc	Section 2.4.1 of the technical specification will be updated to add the word “Micro” before ATX.
3	Doc	Section 1.6.3.3 has been added to the technical specification.
No.	**Plans**	**Errata**
		There are no characterized erratum for this product

Specification Changes

The Specification Changes listed in this section apply to the Intel® Desktop Board DG33TL Technical Product Specification (Order Number: D95738). All Specification Changes will be incorporated into a future version of that specification.

1. Table 1 of the technical specification will be updated to add the word “Micro” before ATX in Form Factor.

Form Factor	Micro ATX (9.60 inches by 9.60 inches [243.84 millimeters by 243.84 millimeters]

2. Section 2.4.1 of the technical specification will be updated to add word “Micro” before ATX.

2.4.1 Form Factor

The board is designed to fit into a Micro ATX-form-factor chassis.

3. Section 1.6.3.3 has been added to the Technical Specification.

1.6.3.3 Intel® Rapid Recover Technology

The Intel® Desktop Board DG33TL incorporates the Intel® Rapid Recover Technology. Intel Rapid Recover Technology is a feature of Intel® Matrix Storage Manager. It uses RAID 1 (mirroring) functionality to copy data from a designated master drive to a designated recovery drive. The master drive data can be copied to the recovery drive either continuously or on request.

When using the continuous update policy, changes made to the data on the master drive while the recovery drive is disconnected or offline are automatically copied to the recovery drive when it is reconnected. When using the on request update policy, the master drive data can be restored to a previous state by copying the data on the recovery drive back to the master drive. The table below provides an overview of the advantages, disadvantages, and the typical usage of Intel Rapid Recover Technology.

Hard Drives Required	2
Advantage	More control over how data is copied between master and recovery drives; fast volume updates (only changes to the master drive since the last update are copied to the recovery drive); member hard drive data can be viewed in Microsoft Windows* Explorer.
Disadvantage	No increase in volume capacity.
Application	Critical data protection; fast restoration of the master drive to a previous or default state.